

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Johshi GOTOH et al.

Application No.: 10/019,299

Art Unit: 2827

Filed: March 11, 2002

Examiner: ALCALA, Jose H.

For UNDERFILLING MATERIAL FOR SEMICONDUCTOR PACKAGE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
United States Patent and Trademark Office  
Washington, DC 20231

Sir:

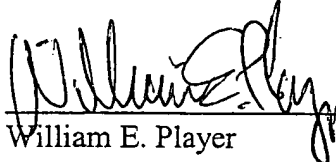
In accordance with 37 CFR 1.56, 1.97, and 1.98, submitted herewith are copies of JP-2000-22048A and a corresponding English language abstract. The submitted reference is listed on the attached Form PTO 1449.

As this statement is being filed before first action on the merits, no fee is required. Should a fee be required, please charge it to Deposit Account No. 06-1358.

Respectfully submitted,

JACOBSON HOLMAN PLLC

By:

  
William E. Player  
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Washington, DC 20004  
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Attorney Docket No. P67440US0

Date: April 11, 2003

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Sheet 1 of 1

FORM PTO 1449 (modified)

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

LIST OF REFERENCES CITED BY APPLICANT(S)  
(Use several sheets if necessary)

Date Submitted to PTO: April 11, 2003

ATTY DOCKET NO.: P67440US0

SERIAL NO.: 10/019,299

APPLICANT: Johshi GOTOH et al.

FILING DATE: March 11, 2002

GROUP: 2827

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
JP2000-220481	01-21-2000	JAPAN			X

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)


EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>Notice of References Cited</b>	Application/Control No. 10/019,299	Applicant(s)/Patent Under Reexamination GOTOH ET AL.	
	Examiner Jose H Alcala	Art Unit 2827	Page 1 of 2

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-4,499,149	02-1985	Berger, Abe	428/447
	B	US-5,929,512	07-1999	Jacobs, Richard L.	257/667
	C	US-6,492,204	12-2002	Jacobs, Richard	438/127
	D	US-6,406,990	06-2002	Kawai, Wakahiro	438/612
	E	US-5,386,624	02-1995	George et al.	29/832
	F	US-5,390,082	02-1995	Chase et al.	361/783
	G	US-5,450,283	09-1995	Lin et al.	361/704
	H	US-5,533,256	07-1996	Call et al.	29/840
	I	US-5,804,882	09-1998	Tsukagoshi et al.	257/783
	J	US-5,288,944	02-1994	Bronson et al.	174/52.4
	K	US-5,249,101	09-1993	Frey et al.	361/717
	L	US-5,641,996	06-1997	Omoya et al.	257/787
	M	US-6,507,101	01-2003	Morris, Terrel L.	257/706

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.

**Notice of References Cited**

Application/Control No.

10/019,299

Applicant(s)/Patent Under

Reexamination

GOTOH ET AL.

Examiner

Jose H Alcala

Art Unit

2827

Page 2 of 2

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-6,534,858	03-2003	Akram et al.	257/706
	B	US-6,252,308	06-2001	Akram et al.	257/787
	C	US-6,121,070	09-2000	Akram, Salman	438/108
	D	US-6,037,043	03-2000	Lehner et al.	428/209
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

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Sheet 1 of 1

FORM PDS 1449 (modified)

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE  
USPTO REFERENCE CITED BY APPLICANT(S)  
(Use cover sheet if necessary)

Date of Filing: March 25, 2002

ATTY DOCKET NO.:

P67440US0

SERIAL NO.:

10/019,299

APPLICANT: Johshi GOTOH et al.

FILING DATE: January 7, 2002

GROUP: Unassigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
JHA	5,061,776	10/1/91	WEAVER et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
JHA	JP2713760-B	03/1/90	JAPAN (English Abstract)			
JHA	JP2738487-B	03/1/94	JAPAN (English Abstract)			
JHA	JP10204259-A	03/1/98	JAPAN (English Abstract)			
JHA	WO 98/31738	01/1/98	PCT			
JHA	EP 0757067A1	03/1/95	EUROPEAN			

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

JHA	"Solder Joint Life Improvement Using Adhesive Under Component", Research Disclosure - 2244 - (January, 1990) No. 309, New York, US - XP 000099320

EXAMINER

John H. Alde

DATE CONSIDERED

5/5/03

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Sheet 1 of 1

FORM PTO 1449 (modified)

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICELIST OF REFERENCES CITED BY APPLICANT(S)  
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For: UNDERFILLING MATERIAL FOR SEMICONDUCTOR PACKAGE

**INFORMATION DISCLOSURE STATEMENT**

Commissioner of Patents  
Washington, DC 20231

Sir:

As a means of complying with the duty of disclosure under 37 CFR §1.56, and in accordance with 37 CFR §§1.97 and 1.98, Applicant(s), through the undersigned attorney, submits this Information Disclosure Statement. The patents, publications or other information submitted herewith are listed on the attached Form PTO-1449 and copies are attached. Cited in the International Search Report (copy attached) are WO 98/31738 A, EP O 757 067A, US 5,061,776 , and "SOLDER JOINT LIFE IMPROVEMENT USING ADHESIVE UNDER COMPONENT" page 32. JP-10-204259-A is cited and discussed in the present specification.

In accordance with 37 CFR §1.97(b)(1) or (2), this Information Disclosure Statement is being filed either within three months of the filing date of the above-identified application, or

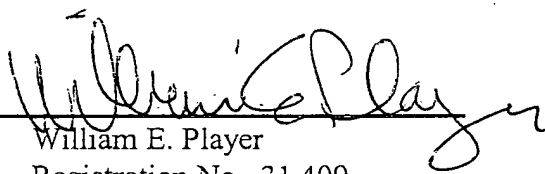
U.S. Patent Application No.: 10/019,299  
Attorney Docket No.: P67440US0

within three months of the date of entry into the national stage of the above-identified application  
as set forth in 37 CFR §1.491. Accordingly, no fee is required.

Respectfully submitted,

JACOBSON HOLMAN PLLC

By:



William E. Player

Registration No. 31,409

Dated: March 25, 2002

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WEP/rdt

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Sheet 1 of 1

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